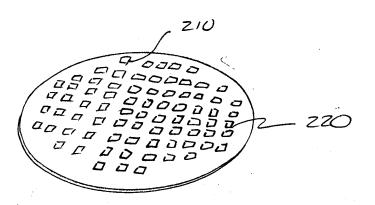


Fig. 1



F192

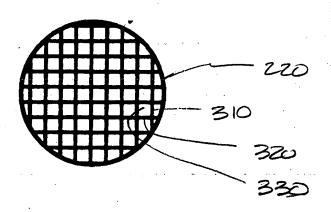
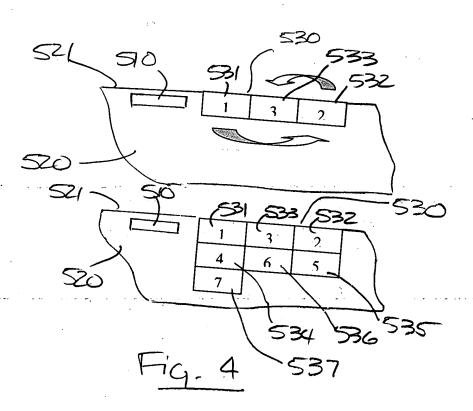
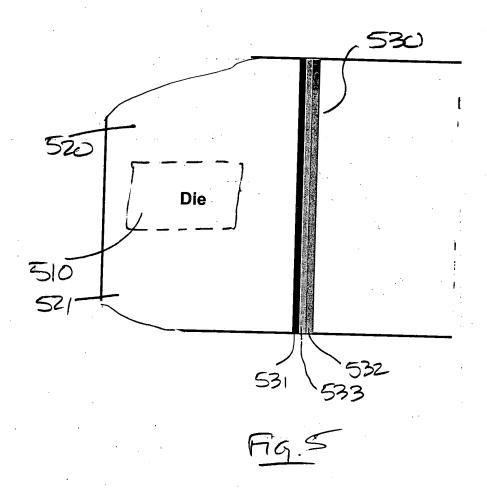


Fig.3





laser scribing a first continuous line

70

Take the first continuous line spaced apart from the first continuous line

714

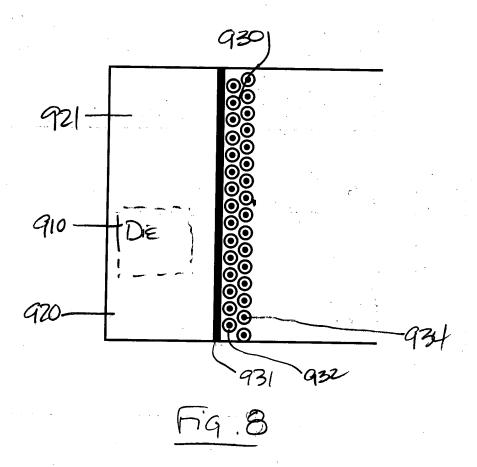
laser scribing a third continuous line, the third continuous line positioned between the first continuous line and the second continuous line

Fia. 6

laser scribing a first continuous line

| 812 |
| laser scribing a second continuous line spaced apart from the first continuous line |
| 814 |
| laser scribing a third continuous line, the third continuous line positioned between the first continuous line and the second continuous line |
| 816 |
| passing a saw through the area of the first continuous line, the second continuous line and the third continuous line to cut the wafer

Fig. 7

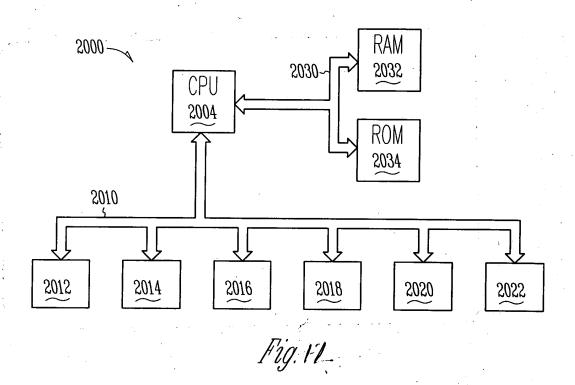


laser scribing a continuous line 1012 laser ablating an area adjacent the laser scribed continuous line, the laser ablations in the area adjacent the laser scribed continuous line being spaced from one another.

laser scribing a continuous line on each side of the die

laser ablating an area adjacent the laser scribed continuous line on each side of the die, the laser ablations in the area adjacent the laser scribed continuous line on each side of the die being spaced from one another

sawing the laser ablated area adjacent the continuous line



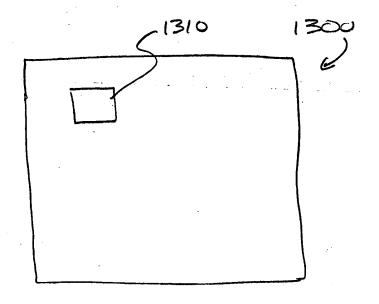


Fig.12